

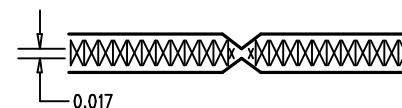
SHOWN FROM COMPONENT SIDE

REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		


SIZE	QTY	SYM	PLTD
0.02	153	+	PLTD
0.094	8	×	PLTD
0.07	3	□	NPLTD
0.12	2	◇	PLTD

NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD
 THICKNESS .062 +/- .006 TOTAL OF 2 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE
 ELECTRODEPOSITED TIN-LEAD COMPOSITION
 BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. FILL UP ALL VIAS WITH SOLDER.
7. SCORING:



8. PLEASE LOOK AT THE README FILE FOR THE OTHER REQUIREMENTS.

APPROVALS				LINEAR TECHNOLOGY	1630 McCarthy Blvd Milpitas, CA 95035 PH: (408)432-1900
	INIT	DATE			
DRAWN					
CHECK					
DESIGN	KIM T.	08-21-00	TITLE: Fabrication Drawing 400MHZ I/Q DEMODULATOR		
ENGR	VLADIMIR D.	08-21-00			
			SIZE	DEMO	REV.
			A	DC333A-2*LT5502GN	A
SCALE = NONE			DES- 0000		SHT 1 of 1